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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: SLUZEWSKI ET AL. Examiner: C. RENNER
Serial No.: 09/455,851 Group Art Unit: 2652
Filed: DECEMBER 7, 1999 Docket No.: SEA8994/30874.87USU1
Title: SLIDER SCALE PACKAGE FOR MAGNETIC RECORDING HEADS

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited in the United States Postal Service, as first class mail, with sufficient postage, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on January 29, 2002.

By:

Name:

RESPONSE

Commissioner for Patents
Washington, D.C. 20231

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Dear Sir:

Technology Center 2600

In an Office Action dated November 29, 2001, the Examiner has required the Applicants under 35 U.S.C. § 121 to elect a single disclosed species and subspecies, if applicable. While Applicants must make an election, Applicants do not believe that an election is necessary.

Claims to be restricted to different species must be mutually exclusive. The general test as to when claims are restrictive, respectively, to different species is the fact that one claim recites limitations which under the disclosure are found in a first species but not in a second, and another claim recites limitations disclosed only for the second species and not the first.

Independent claim 1 calls for, inter alia, "means for attaching to a back of the slider/MR head which turns the slider/MR head into the slider scale package assembly with at least one interconnect pad disposed at the back of the slider/MR head." (emphasis added) Independent claim 2 calls for, inter alia, "a flex circuit attached to a back of the slider/MR head which turns the slider/MR head into the slider package assembly with at least one interconnect pad disposed at the back of the slider/MR head." (emphasis added) Independent claim 15 also calls for, inter alia, "a slider scale package . . . comprises a flex circuit attached to a back of the slider/MR

head . . . without at least one interconnect pad disposed at the back of the slider/MR head . . ." (emphasis added) In the specification of the subject application, it is stated with respect to Fig. 3 "as shown, the interconnect pad 150 is positioned at the back of the slider/MR head 142 and is electrically bonded to the conductive material 134 of the head interconnect circuit 130." (page 3, lines 21-23) With respect to Figure 7 it is stated, "as shown, the interconnect pad 164 is positioned at the back of the slider/MR head 156" (page 14, lines 22-23) With respect to Figure 10, it is stated "as shown, the interconnect pad 100 is positioned at the back of the slider/MR head 170" And finally, with respect to Figure 11, it is stated "as shown, the interconnect pad 196 is positioned at the back of the slider/MR head 186" (page 16, lines 12-13)

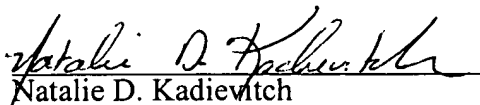
Thus the language in each of claims 1, 2 and 15 as described above can be read on all of the embodiments of the subject application. While the Examiner states that claim 1 is generic, Applicants believe that claims 2 and 15 are also generic.

While Applicants do not agree with the election requirement, Applicants elect Figure 3 and corresponding claims 1-4, 8-12, and 15-18.

Respectfully submitted,

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Date: January 29, 2002


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